

Parameter	Rating	Units
Blocking Voltage	350	V _P
Load Current	120	mA _{rms} / mA _{DC}
On-Resistance (max)	30	Ω

Features

- 1500V_{rms} Input/Output Isolation
 Low Drive Power Requirements
- High Reliability
- No EMI/RFI Generation
- Small 4-Pin SOP Package
- Tape & Reel Version Available
- Flammability Rating UL 94 V-0

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - · Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- · Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Industrial Controls

Description

The CPC1130N is a miniature normally-closed, single-pole (1-Form-B) solid state relay that uses optically coupled MOSFET technology to provide $1500 \rm{V}_{\rm{rms}}$ of input to output isolation. The efficient MOSFET switches and photovoltaic die use IXYS Integrated Circuits' patented OptoMOS® architecture while the optically coupled output is controlled by a highly efficient infrared LED.

The CPC1130N offers board space savings of at least 20% when compared to competitive 4-pin SOP solid state relays.

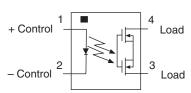
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- TUV EN 62368-1: Certificate # B 082667 0008

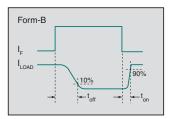
Ordering Information

Part #	Description
CPC1130N	4-Pin SOP (100/tube)
CPC1130NTR	4-Pin SOP (2000/reel)

Pin Configuration



Switching Characteristics of Normally-Closed Devices











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	Α
Input Power Dissipation 1	150	mW
Total Power Dissipation ²	400	mW
Isolation Voltage, Input to Output	1500	V _{rms}
Operational Temperature, Ambient	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics				'		'
Blocking Voltage	$I_L=1\mu A$	V_{DRM}	350	-	-	V
Load Current	_					
Continuous 1	-	I _I	-	-	120	mA_{rms} / mA_{DC}
Peak	t =10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ²	I _L =120mA	R _{ON}	-	25	30	Ω
Off-State Leakage Current	$I_F=2mA, V_L=350V_P$	I _{LEAK}	-	-	5	μΑ
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	-	2	mo
Turn-Off		t _{off}	-	-	2	ms
Output Capacitance	I_F =2mA, V_L =50V, f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics						
Input Control Current to Activate 3	I _L =120mA	I _F	-	0.6	2	mA
Input Control Current to Deactivate	-	I _F	0.3	0.55	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.36	1.5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ
Common Characteristics						
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	1	-	pF

Load current derates linearly from 120mA @ 25°C to 80mA @ 85°C.

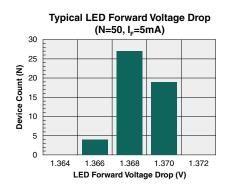
² Derate output power linearly 3.33 mW / °C

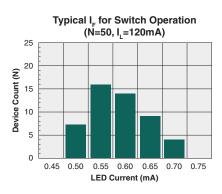
Measurement taken within 1 second of on-time.

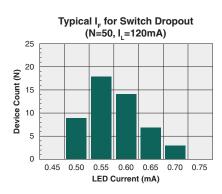
For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 4mA is recomended.

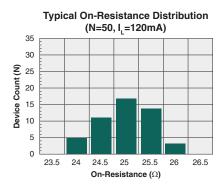


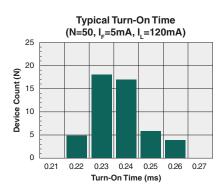
PERFORMANCE DATA*

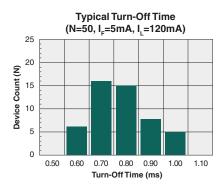


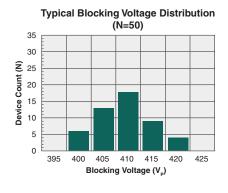


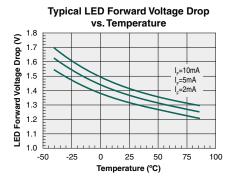


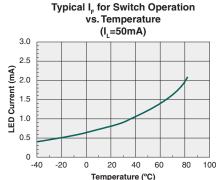


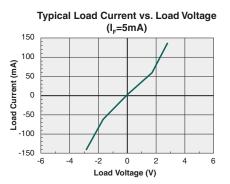






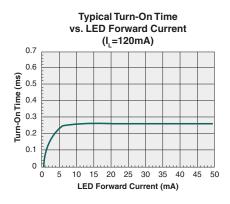


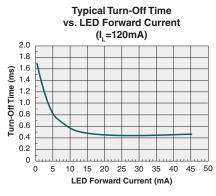


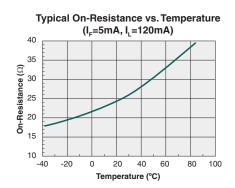


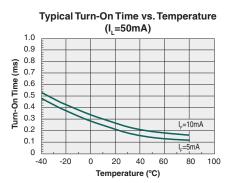


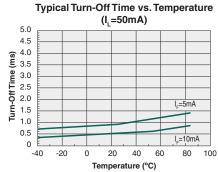
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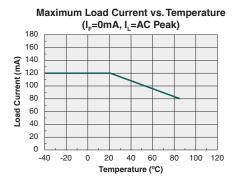


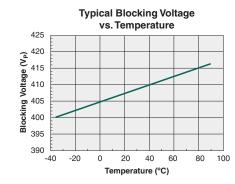


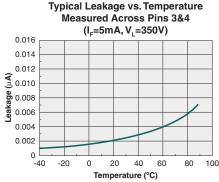


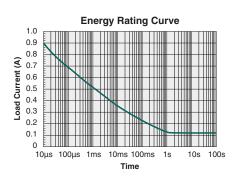














Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression, IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and quarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1130N	MSL 3

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the IPC/JEDEC J-STD-020 Classification Temperature (T_C) and the maximum dwell time the body temperature of these surface mount devices may be (T_C - 5)°C or greater. The Classification Temperature sets the Maximum Body Temperature allowed for these devices during reflow soldering processes.

Device	Classification Temperature (T _c)	Dwell Time (t _P)	Max Reflow Cycles
CPC1130N	260°C	30 seconds	3

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.



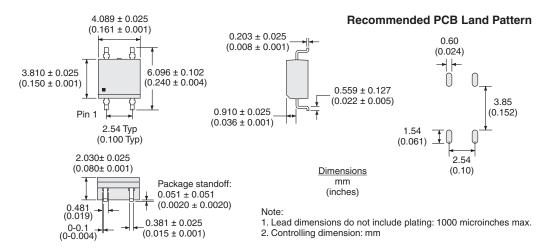




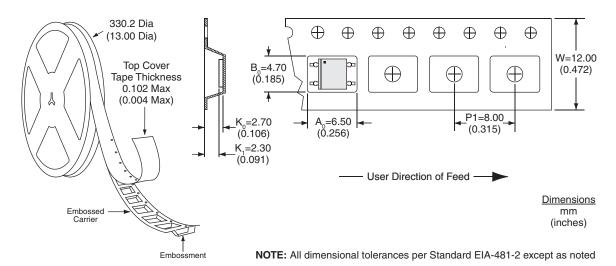


MECHANICAL DIMENSIONS

CPC1130N



CPC1130NTR Tape & Reel



For additional information please visit our website at: https://www.ixysic.com



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